



## Material Content Data Sheet



<b>Sales Product Name</b>		BSG0810NDI		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001288598						
<b>Package</b>		PG-TISON-8-4		<b>Weight*</b>		111.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.421	0.38	0.38	3769	3769
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	zinc	7440-66-6	0.043	0.04		386	
	non noble metal	iron	7439-89-6	0.862	0.77		7716	
wire	non noble metal	copper	7440-50-8	34.984	31.33	32.15	313293	321491
	non noble metal	copper	7440-50-8	0.010	0.01	0.01	85	85
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.09		852
	plastics	epoxy resin	-	4.897	4.39		43856	
	inorganic material	silicondioxide	60676-86-0	42.554	38.08	42.56	381083	425791
leadfinish	non noble metal	tin	7440-31-5	1.180	1.06	1.06	10565	10565
plating	noble metal	silver	7440-22-4	0.087	0.08	0.08	775	775
solder	noble metal	silver	7440-22-4	0.019	0.02		166	
	non noble metal	tin	7440-31-5	0.015	0.01		133	
	non noble metal	lead	7439-92-1	0.709	0.64	0.67	6352	6651
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.008	0.01		69	
	non noble metal	zinc	7440-66-6	0.031	0.03		277	
	non noble metal	iron	7439-89-6	0.619	0.55		5541	
	non noble metal	copper	7440-50-8	25.123	22.50	23.09	224986	230873
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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